ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN20889D
Issue Date: 4 June 2015

Title of Change:	WLP fab site change from Gunma, Japan to Niigata, Japan
Proposed first ship date:	29 August 2016
Contact information:	Contact your local ON Semiconductor Sales Office or Minoru.Akaishi@onsemi.com
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or Makoto.Nakaoka@onsemi.com
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Product lots will be identified through a date code marked on the parts

Change category(s):

- ☐ Wafer Fab Change
- ☐ Assembly Change
- ☐ Test Change
- ☒ Manufacturing Site Change/Addition
- ☐ Manufacturing Process Change
- ☐ Material Change
- ☐ Product specific change
- ☐ Datasheet/Product Doc change
- ☐ Shipping/Packaging/Marking
- ☐ Other: _____

Sites Affected:	Site 1	Site 2
☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ☐ External Foundry/Subcon site(s):	ON Niigata, Japan	

Description and Purpose:

To be able to continuously supply products and increase our supply capacity to support increased demand, WLP site will be changed from Gunma, Japan to Niigata, Japan. All equipment and most personnel will be transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified. Neither change in electrical characteristics, nor change in product reliably is expected

Qualification Plan:

Estimated date for qualification completion: 27 May 2016

IC Reliability Plan

1.0

REFERENCE DOCUMENTS: 12MSB17722C - Product Reliability Qualification Process Specification

2.0

WLP/FLIP Reliability Plan
Fab site change from Gunma, Japan to Niigata, Japan

3.0

Package	WLCSP179 WLCSP36 WLFCP6	Wafer Fab Site	Niigata

4.0

RELIABILITY TESTING REQUIREMENTS

Test	Test Conditions	End Point Requirements	Sample Size	# of Lots	Total Units	Comments
HTOL	TJ ~ 150°C, for 1008 hrs	Test @ Room	77	3	231	
HTSL	150°C for 1008 hrs	Test @ Room	77	3	231	
THB	85°C/85% RH for 1008 hrs	Test @ Room	77	3	231	
TC	-40°C to +125°C for 500 cycles	Test @ Room	77	3	231	

Samples should be available after completion of Qualification.

List of affected Standard Parts:

LC709203FXE-01MH
LV5216CS-TE-L-E
LV8414CS-N-TE-L-H
LV8498CT-TE-L-H